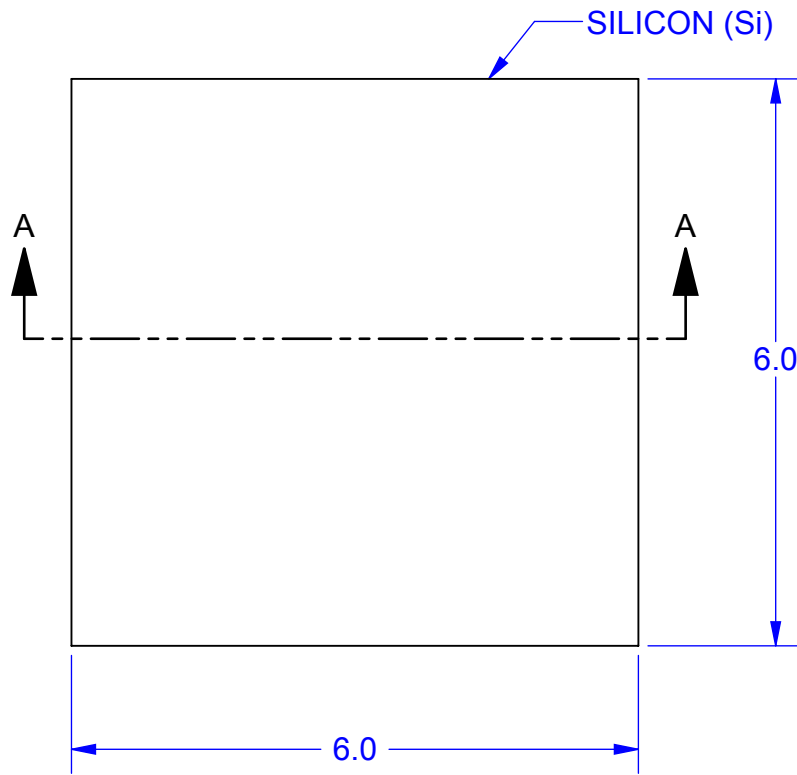
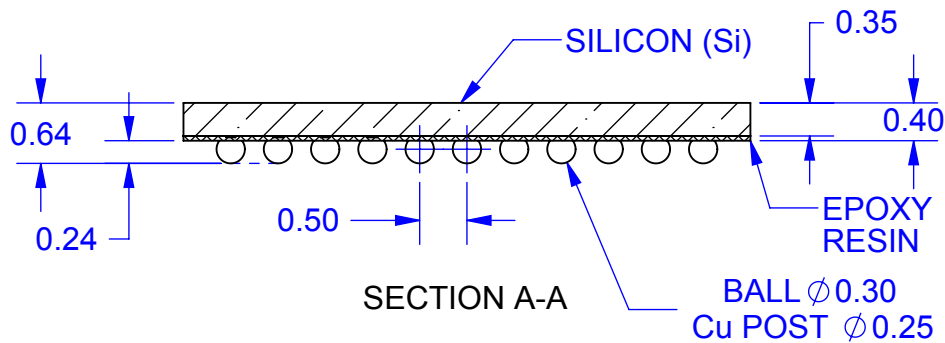
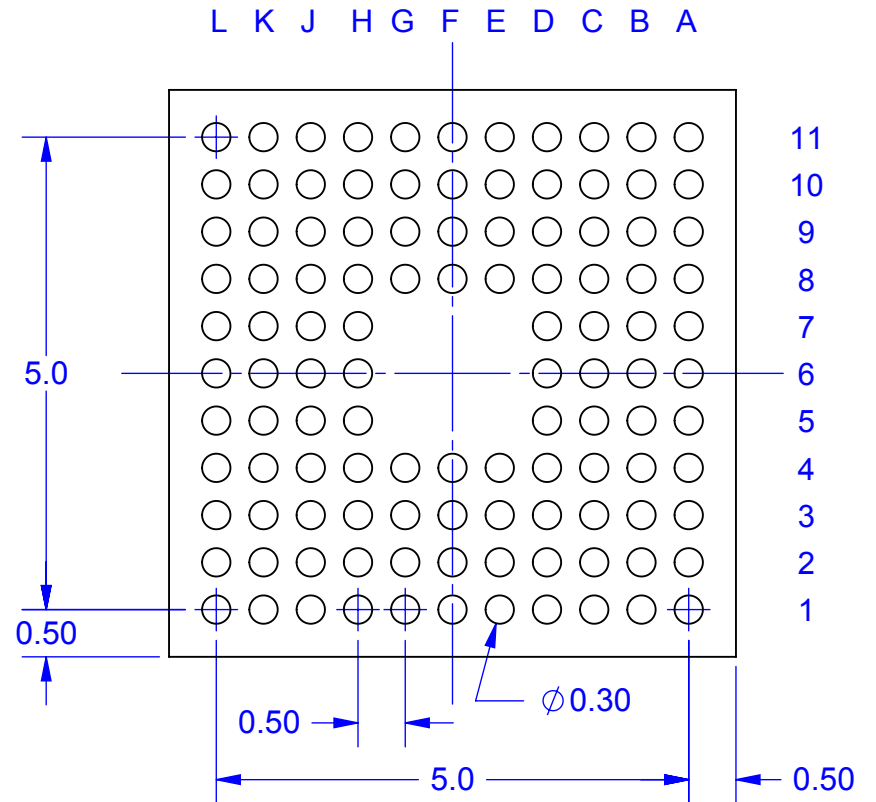


TOP VIEW



BALL VIEW



Notes: (Unless Otherwise Specified).

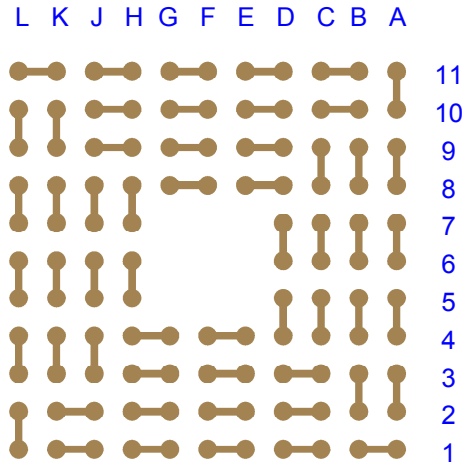
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.25mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN IS OMNI-DIRECTIONAL. (SEE PAGE 2)
- 8) PIN A1 MARKING IS NOT REQUIRED.

| PART NUMBER TABLE | | | | |
|-------------------|--------------------|---------|------|--------|
| PART NUMBER | BALL ALLOY | Pb-FREE | RoHS | Si DIE |
| WLP112T.5C-DC113D | Sn96.5/Ag3.0/Cu0.5 | YES | YES | YES |

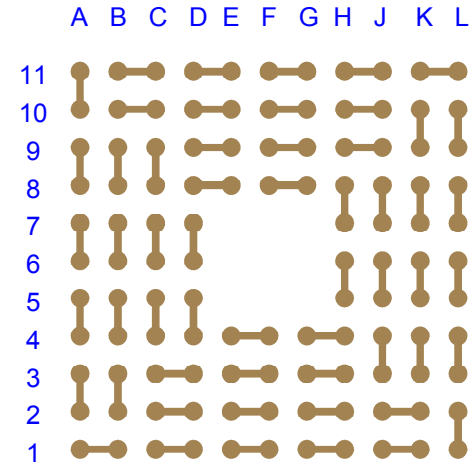
| | | | | | |
|-------------|----------|----------------------|-------------------|-------------|--------------|
| APPROVALS | DATE | TopLine® | | | |
| DRAWN T. Au | 12/22/12 | | | | |
| ENG M. Hart | 12/22/12 | TITLE | WLP112T.5C-DC113D | | |
| MFG | | | 112-BALL P=0.5mm | | |
| QA | | SCALE | SIZE | DRAWING NO. | REV |
| CUST | | 12.5:1 | A | 551132 | A |
| REVISED | | DO NOT SCALE DRAWING | | | SHEET 1 OF 2 |

DAISY CHAIN PATTERN

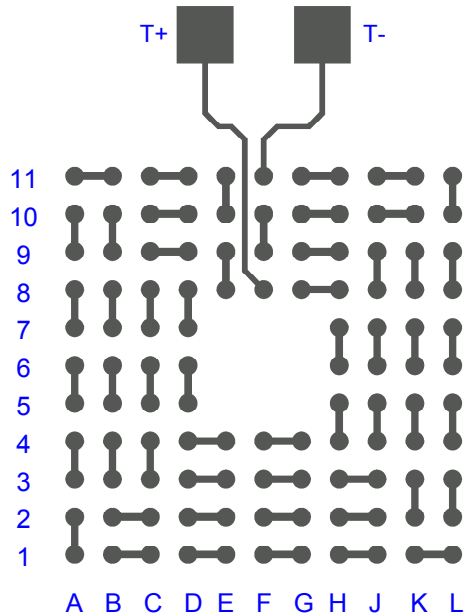
BALL VIEW



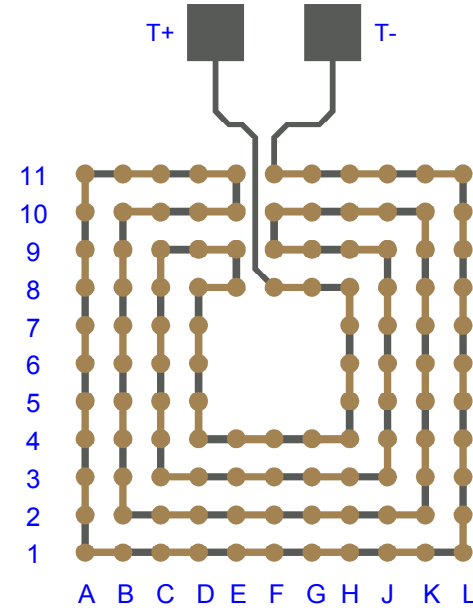
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.25mm (9.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

| | | | |
|----------------------|------|---------------------------------------|--------------|
| TopLine® | | | |
| TITLE | | WLP112T.5C-DC113D 112-BALL P=0.5mm | |
| SCALE | SIZE | DRAWING NO. | REV |
| 10:1 | A | 551132 | A |
| DO NOT SCALE DRAWING | | | SHEET 2 OF 2 |